

ABSTRACT

A method and device are provided to realize a structure in which different kinds of chips are three-dimensionally mounted while suppressing the warpage of a carrier substrate. A semiconductor package PK12 in which stacked semiconductor chips 33a and 33b are wire-bonded to the carrier substrate 31 is stacked on a semiconductor package PK11 in which semiconductor chips 23a and 23b are mounted on both faces of the carrier substrate 21 by ACF bonding.